

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3003890

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHUICHI TSUKADA	05/28/2014
RECEIVING PARTY DATA	
Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 SOUTH FEDERAL WAY
City:	BOISE
State/Country:	IDAHO
Postal Code:	83716-9632
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14473489
CORRESPONDENCE DATA	
Fax Number:	
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ATTORNEY DOCKET NUMBER:	P245556.US.01
NAME OF SUBMITTER:	KIMTON ENG
SIGNATURE:	/Kimton Eng/
DATE SIGNED:	08/29/2014
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 2	
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source=Assignment_082914_ELPA-0020#page2.tif	

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Shuichi TSUKADA

Filed : Concurrently herewith

For : SEMICONDUCTOR DEVICE

Docket No. P245556.US.01

Micron Disclosure No. ELPA-0020.00/US

ASSIGNMENT:

Enclosed for recording
 Previously recorded

Date: _____

Reel: _____

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned do hereby:

SELL, ASSIGN AND TRANSFER to **Micron Technology, Inc.** (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83716-9632, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled
" SEMICONDUCTOR DEVICE "

which claims priority to JP patent application, filed on August 29, 2013, assigned Application No. 2013-178337 and is entitled
" SEMICONDUCTOR DEVICE "

such application and any legal equivalent thereof in a foreign country, including the right to claim priority and, in and to, all Letters Patent to be obtained for said invention by the above application or any and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee; to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Signature: Shuichi Tsukada
Assignor Name: Shuichi TSUKADA

Date: 2014, 5, 28

Witness # 1:
Signature: [Handwritten Signature]

Date: May 28, 2014

Witness Name: _____